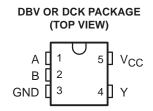
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- Qualification in Accordance With AEC-Q100[†]
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Operating Range of 2 V to 5.5 V
- Max t_{pd} of 6.5 ns at 5 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±8-mA Output Drive at 5 V
- Schmitt-Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time

[†] Contact factory for details. Q100 qualification data available on request.

description/ordering information

- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



The SN74AHC1G00 performs the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

т _А	PACKAGI	±‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
4000 1- 0500	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G00IDBVRQ1	A00U
–40°C to 85°C	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G00IDCKRQ1	AAU
-40°C to 125°C	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G00QDBVRQ1	A00U
-40 C to 125°C	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G00QDCKRQ1	AAU

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INP	UTS	OUTPUT
Α	В	Y
Н	Н	L
L	Х	Н
Х	L	Н

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Note 1)0.5 Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) Continuous output current, I_O ($V_O = 0$ to V_{CC}) Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2): DBV package DCK package	$\begin{array}{c} -0.5 \ V \ to \ 7 \ V \\ V \ to \ V_{CC} + 0.5 \ V \\ -20 \ mA \\ \dots & \pm 20 \ mA \\ \dots & \pm 25 \ mA \\ \dots & \pm 50 \ mA \\ \dots & 206^\circ C/W \\ \dots & 252^\circ C/W \end{array}$
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	V
		$V_{CC} = 2 V$	1.5		
VIH	High-level input voltage	V _{CC} = 3 V	2.1		V
		V _{CC} = 5.5 V	3.85		
		$V_{CC} = 2 V$		0.5	
VIL	Low-level input voltage	V _{CC} = 3 V		0.9	V
		V _{CC} = 5.5 V		1.65	
VI	Input voltage		0	5.5	V
VO	Output voltage		0	VCC	V
		V _{CC} = 2 V		-50	μA
ЮН	High-level output current	V _{CC} = 3.3 V ± 0.3 V	-4		
		$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V _{CC} = 2 V		50	μΑ
IOL	Low-level output current	V _{CC} = 3.3 V ± 0.3 V		4	
		$V_{CC} = 5 V \pm 0.5 V$		8	mA
Δt/Δv		V _{CC} = 3.3 V ± 0.3 V	10		
	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$	1	20	ns/V
-		l suffix	-40	85	<u></u>
TA	Operating free-air temperature	Q suffix	-40	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST CONDITIONS	VCC	T _A = 25°C		T _A = −40°C TO 125°C		T _A = −40°C TO 85°C		UNIT		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
		2 V	1.9	2		1.9		1.9			
	I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9			
VOH		4.5 V	4.4	4.5		4.4		4.4		V	
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		2.48			
	IOH = -8 mA	4.5 V	3.94			3.8		3.8			
		2 V			0.1		0.1		0.1		
	I _{OL} = 50 μA	3 V			0.1		0.1		0.1		
VOL		4.5 V			0.1		0.1		0.1	V	
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44		
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44		
Ц	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	μA	
ICC	$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	5.5 V			1		10		10	μA	
Ci	$V_I = V_{CC}$ or GND	5 V		2	10		10		10	pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)			ς = 25°C	;	T _A = - TO 12		T _A = - TO 8		UNIT		
	(INPOT)	(001701)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX			
^t PLH	A	X	0. 45		5.5	7.9	1	11.5	1	9.5			
^t PHL	A or B	ř	C _L = 15 pF	CL = 15 pF			5.5	7.9	1	11.5	1	9.5	ns
^t PLH	A or D	V	C: 50 pF		8	11.4	1	15	1	13			
^t PHL	A or B	Ť	C _L = 50 pF		8	11.4	1	15	1	13	ns		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

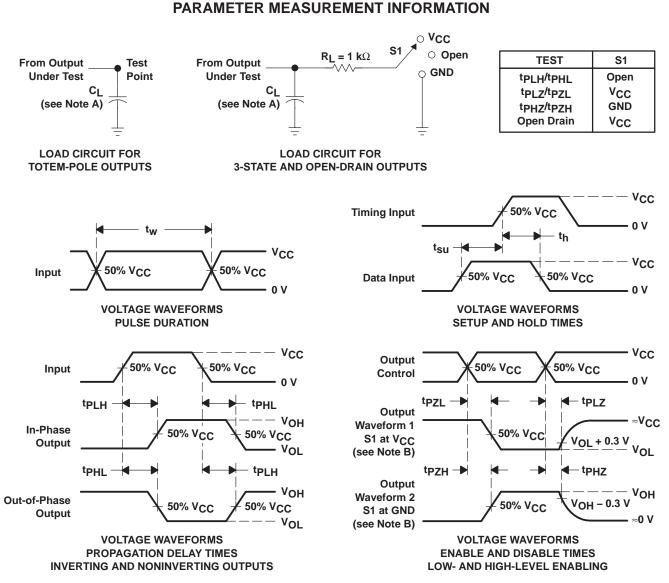
PARAMETER	FROM	TO			₄ = 25°C	;	T _A = - TO 12		T _A = - TO 8		UNIT		
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX			
^t PLH	A or D	X	0 45 55		3.7	5.5	1	8.5	1	6.5			
^t PHL	A or B	ř	C _L = 15 pF	$C_L = 15 \text{ pF}$		3.7	5.5	1	8.5	1	6.5	ns	
^t PLH	A or B	v	$C_{1} = 50 \text{ pF}$		5.2	7.5	1	10.5	1	8.5			
^t PHL	AUB	T	C _L = 50 pF	CL = 50 pr	CL = 50 pF		5.2	7.5	1	10.5	1	8.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load,	f = 1 MHz	9.5	pF



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NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_r \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHC1G00QDCKRQ1	ACTIVE	SC70	DCK	5	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.



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